## DECLARATION FOR U.S. PATENT APPLICATION

As a below named inventor, I hereby declare that:

03-W-08 (MP/BZ5103-P-US)

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

SP3-BONDED BORON NITRIDE EMITTING LIGHT IN ULTRAVIOLET

| USING                                   | G THE SAME   | HOD OF THE SA             | AME, AND FUNCTIO                 | NAL MATERIAL                          |
|---|--|---------------------------|----------------------------------|---------------------------------------|
|   | n of which is attached hereto u<br>July 1, 2003  | _                         |                                  |                                       |
| Number                                  | as United States A   | Application Number or I   | PCT International Application    | ι                                     |
| I hereby state th                       | JPO3/08370  nat I have reviewed and undersended by any amendment refer   | stand the contents of the | •                                | ı, including the                      |
| I acknowledge t<br>Federal Regulat      | the duty to disclose informatio<br>tions, § 1.56.  | n which is material to pa | ntentability as defined in Title | : 37, Code of                         |
| ~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~ | foreign priority benefits under<br>or patent or inventor's certifica<br>or's certificate having a filing   | ITE IISTEN NEINW 200 HOVA | olen identified belam, sav. fa.  |                                       |
| (List prior foreign                     | 0.00   |                           |                                  | Priority Claimed                      |
| applications. Sec<br>note A)            | 2002-192863  | Japan                     | 02/07/02                         | Yes No                                |
|   | (Number)   | (Country)                 | (Day/Month/Year Filed)           |                                       |
|   | (Number)   | (Country)                 | (Day/Month/Year Filed)           | Yes No                                |
|   | (Number)   | (Country)                 | (Day/Month/Year Filed)           | Yes No                                |
|   | (Number)   | (Country)                 | (Day/Month/Year Filed)           | Yes No                                |
| See note B)                             | See attached list for additional   | prior foreign application | ns                               |                                       |
| ipplication in the                      | the benefit under Title 35, Un<br>the subject matter of each of<br>the manner provided by the fir<br>information which is material<br>ecame available between the first<br>sapplication. | st paragraph of Title 35  | United States Code, § 112        | prior United States, Lacknowledge the |
| List prior U.S.                         |  |                           | Statu                            | s                                     |
| ·<br>                                   | (Application Serial No.)   | (Filing Date)             | Patented Pendi                   | ing Abandoned                         |
|   | (Application Serial No.)   | (Filing Date)             | Patented Pendi                   | ng Abandoned                          |
| -                                       | (Application Serial No.)   | (Filing Date)             | Patented Pendi                   | ng 🔲 Abandoned                        |
|   | (Application Serial No.)   | (Eiling Dass)             | Patented Pendi                   | ng 🗌 Abandoned                        |

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Palent and Trademark Office connected therewith:

Westerman, Hattori, Daniels & Adrian, LLP, a firm composed of William P. Westerman (Reg. No. 29,988); Ken-Ichi Hattori (Reg. No. 32,861); Scott M. Daniels (Reg. No. 32,562); Stephen G. Adrian (Reg. No. 32,878); Thomas J. Macpeak (Reg. No. 19,292); John P. Kong (Reg. No. 40,054); Sadao Kinashi (Reg. No. 48,075); Nicolas E. Seckel (Reg. No. 44,373); Edward F. Kenehan, Jr. (Reg. No. 28,962); Thomas E. Brown (Reg. No. 44,450); Joseph L. Felber (Reg. No. 48,109); Kenneth H. Salen (Reg. No. 43,077); and Michael N. Lau (Reg. No. 39,479)

Please direct all communications to the following address:

- LLS tomer N. 38834

Westerman, Hattori, Daniels & Adrian, LLP, P.O. Box 33275, Washington, D.C. 20033-3275

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

|             | <b>2010011.</b>                         |  |  |
|-------------|---|--|--|
| See note C) |   | irst inventor, (given name, family name) | Shojiro KOMATSU                        |
| •           | Inventor's signature                    | Sh. Kom atsur                            | Date November 10, 2004                 |
|             | Residence Same                          | as post office address                   | Citizenship Japan                      |
| •           | Post Office Address                     | c/o NATIONAL INSTITUTE                   | FOR MATERIALS SCIENCE.                 |
|             | •                                       | <del></del>                              | sukuba-shi, IBARAKI 305-0047JPA        |
|             | •                                       | JAPAN                                    |  |
|             | Full name of second is                  | nventor (given same) family hame)        | Katsuyuki OKADA                        |
|             | Inventor's signature                    | 2 Cakada                                 | Date November 10, 2004                 |
|             | Residence Same                          | as post office address                   | Citizenship Japan                      |
|             | Post Office Address                     | c/o NATIONAL INSTITUTE                   | FOR MATERIALS SCIENCE,                 |
|             | •                                       |  | sukuba-shi, IBARAKI 305-004750×        |
|             |   | JAPAN                                    |  |
|             | Full name of third inv                  | entor (given game, family name)          | Yusuke MORIYOSHI                       |
|             | Inventor's signature                    | yusukl hondad                            | Date November 10, 2004                 |
|             | Residence Same                          | as post office address                   | Cidzenship Japan                       |
|             | Post Office Address                     | c/o HOSEI UNIVERSITY                     | The Faculty of Engineering, TPX        |
|             |   | 7-2, Kajinocho 3-chome                   | , <u>Koganei-shi, TOKYO 184-0002</u> ~ |
|             |   | JAPAN                                    |  |
|             | Full name of fourth in                  | iventor (given name, family name)        |  |
|             | Inventor's signature Residence          | · · · · · · · · · · · · · · · · · · ·    | Date                                   |
|             | Post Office Address                     |  | Citizenship                            |
| •           | rost Office Addless                     |  |  |
| ,           | •                                       |  |  |
|             |   |  |  |
|             | Full name of fifth inventor's signature | entor (given name, family name)          | Date                                   |
|             | Residence                               |  | Citizenship                            |
|             | Post Office Address                     |  | Cidzenship                             |
|             | × 001 011100 11001000                   | <del></del>                              |  |
|             | , · ·                                   | :  |  |
|             | Toll some of short land                 |  |  |
|             | Inventor's signature                    | entor (given name, family name)          | Date                                   |
|             | Residence                               |  | Citizenship                            |
|             | Post Office Address                     |  |  |
|             | •                                       |  |  |
|             | •                                       |  |  |
|             |   |  |  |